

ABSTRACT OF THE DISCLOSURE

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In the case of an LOC semiconductor device, a semiconductor chip is fixed on a die pad through a die pad materiel. A lead including an internal lead extending up to the vicinity of a pad provided to the semiconductor chip is set. A tape member is set to positions corresponding to four corners of the semiconductor chip between the internal lead and the semiconductor chip. The tape member is bonded and fixed only to the internal lead but it is not bonded or fixed to the semiconductor chip and merely contacts with the surface of a semiconductor chip.